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Development, performance and application of novel GaN-based micro-LED arrays with individually addressable n-electrodes

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Abstract - We demonstrate the development, performance and application of a GaN-based micro-light emitting diode array sharing a common p-electrode with individual-addressed n-electrodes. These individually-addressed n-electrodes minimize the series-resistance difference from conductive paths, and offer compatibility with n-type metal-oxide-semiconductor transistor-based drivers for faster modulation.

I. INTRODUCTION

GaN-based micro-light-emitting diode (μ LED) arrays, which consist of a number of μ LED elements with dimensions of less than 100 μ m, possess important novel characteristics. Compared with conventional broad-area LEDs, μ LED elements can be operated at higher current densities, enabling significantly higher modulation bandwidth for data communications applications [1]. By operating a μ LED array in a ganged fashion (multiple μ LED elements modulated simultaneously with the same data signal), a higher signal-to-noise ratio and longer data-transmission distance are expected while retaining fast data rate [2]. This makes μ LED arrays attractive sources for high-speed visible light communications (VLC) in both polymer waveguide and free-space formats.

Standard GaN-based LED epitaxial structures have the p-side of the junction on top. This epi-structure requires that a conventional μ LED array employs a configuration with a common n-electrode and individually addressable p-electrodes for each μ LED element. The main shortcoming of this configuration is that the relevant LED drivers are necessarily based on p-type metal-oxide-semiconductor (PMOS) transistors, which have lower operation speed, larger size and larger capacitance than their n-type equivalents. In addition, this configuration employs the n-type GaN layer as a shared conductive path for all μ LED elements. Different distances between the common n-electrode and the target μ LED element lead to different series resistances contributed from the n-type GaN layer, which results in poor optical element-to-element uniformity and high crosstalk.

In this work, we demonstrate a novel GaN-based μ LED array sharing a common p-electrode with individually addressable n-electrodes. Compared with a conventional μ LED array, the reversed common and individual electrode structure of this configuration minimises the series-resistance difference from conductive paths, and offers compatibility with NMOS-based LED drivers. We have developed and optimised the fabrication process for such arrays to improve performance. At 10.5kA/cm² operating current density, over 414W/cm² optical power density and 345MHz electrical-to-optical (E-O) modulation bandwidth are achieved for a single μ LED element with a diameter of 24 μ m emitting at 450nm. This array was also integrated with a custom NMOS-based driver to demonstrate VLC application. Open eye diagrams were recorded at several hundred Mbps in operation with two μ LED elements under an on-off-keying (OOK) data transmission scheme.

II. FABRICATION PROCESS FOR μ LED ARRAYS

The μ LED arrays developed in this work were fabricated from a commercial blue GaN-based LED wafer on a c-plane sapphire substrate. The μ LED array consists of 6x6 array of flip-chip μ LED elements with a diameter of 24 μ m on a 300 μ m centre-to-centre pitch. Fig.1 shows the main fabrication steps. In order to realize the μ LED array with individually addressed n-electrodes, each μ LED element needs be fully isolated from both p- and n-type GaN layers. To achieve this configuration, two steps of Cl₂-based plasma etching are involved in the fabrication process. Firstly, GaN mesas are etched down to the sapphire substrate [Fig. 1(b)]. Then, a μ LED element is created at the centre of each mesa which stops at the n-type GaN [Fig. 1(c)]. Annealed Pd metal layer is used as a metal contact to p-type GaN. The metallization on the isolated n-type GaN mesa is realized by sputtering a Ti/Au metal bilayer. This bilayer is also patterned to make the metal track from the n-type GaN mesa so as to individually address each μ LED element through the n-electrode. After isolating each μ LED element by a SiO₂ layer, another Ti/Au metal bilayer is used to interconnect μ LED elements forming a shared p-electrode. Fig. 1(g) shows a schematic layout of the whole array to emphasise the common p-electrode and individually addressable n-electrodes. Compared with the conventional μ LED array design, the conductive paths are formed by Ti/Au metal bilayers rather than the n-type GaN layer. Thus, series resistance differences between elements are much reduced owing to the significant lower sheet resistivity of the metal bilayer.

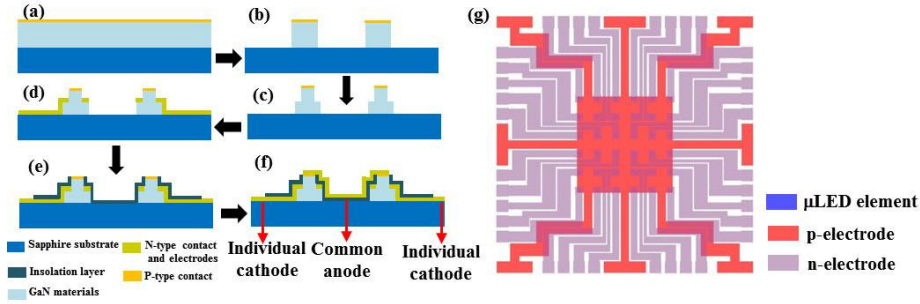


Figure 1: (a)-(f) Schematic diagrams of the fabrication process for the μ LED arrays. Part (g) shows a schematic layout of the whole μ LED array.

III. PERFORMANCE AND APPLICATION OF μ LED ARRAYS

Fig. 2(a) illustrates the current density-voltage and optical power density-current density characteristics of a single μ LED element in the array. This μ LED element can be operated at a direct-current current density up to $10.5\text{kA}/\text{cm}^2$ and is able to produce a continuous wave optical power density over $414\text{W}/\text{cm}^2$. As mentioned, this high operating current density leads to a high modulation bandwidth as shown in Fig. 2(b). This μ LED element has an E-O modulation bandwidth in excess of 350MHz , which is significantly higher than the value of typical commercial LEDs [3]. In order to illustrate the electrical/optical uniformity, the measured current and optical power densities at a fixed voltage of 7V for 5 randomly selected μ LED elements are presented in Fig. 2(c). Analysis of the data reveals the variations of current and optical power densities are within 16.3% and 6.8% , respectively. These variations are mainly caused by the different lengths of metal tracks connecting each μ LED element to its corresponding n-electrode and can be further reduced by increasing the thickness of metal tracks. The μ LED array is further integrated with the custom NMOS-based driver. Detailed information on this driver and integration process can be found in Ref.[2]. Fig. 2(d) shows the open eye-diagram obtained with two μ LED elements operating at 250Mbps under OOK data transmission scheme.

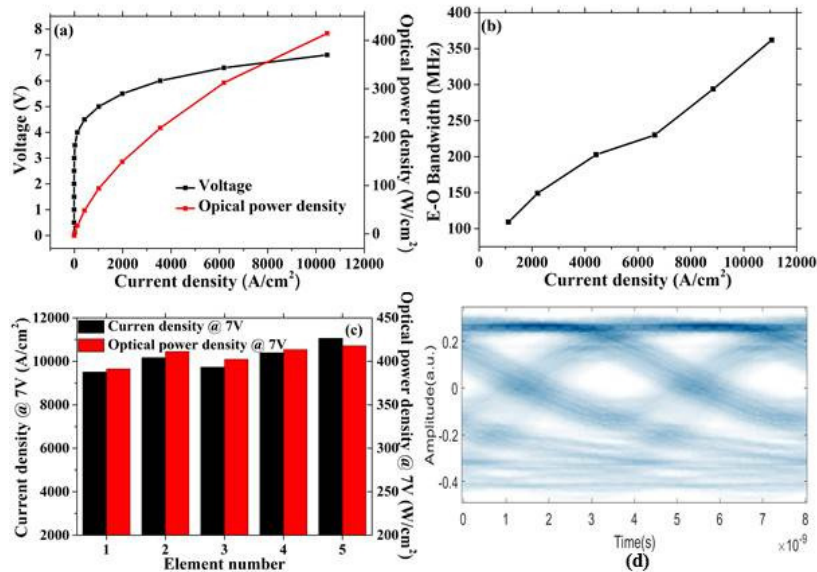


Figure 2: (a) Current density-voltage and optical power density-current density characteristics of a single μ LED element; (b) E-O modulation bandwidth characteristic of the same μ LED element; (c) electrical and optical uniformities of 5 selected μ LED elements in the array; (d) eye-diagram for two μ LED elements operating at 250Mbps under OOK scheme by the NMOS-based driver.

IV. SUMMARY

The fabrication, performance and application of the GaN-based μ LED array sharing a common p-electrode with individual-addressed n-electrodes are demonstrated in this work. The novel configuration enables this array to be compatible with NMOS-based driver for faster modulation. The fabricated μ LED array shows promising performance. The application of this array integrated with an NMOS-based driver in VLC is also presented.

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REFERENCES

1. Ferreira, R.X., et al., *High bandwidth GaN-based micro-LEDs for multi-Gb/s visible light communications*. IEEE Photonics Technology Letters, 2016. **28**(19): p. 2023-2026.
2. Rajbhandari, S., et al., *High-Speed Integrated Visible Light Communication System: Device Constraints and Design Considerations*. IEEE Journal on Selected Areas in Communications, 2015. **33**(9): p. 1750-1757.
3. Vučić, J., et al., *513 Mbit/s visible light communications link based on DMT-modulation of a white LED*. Journal of Lightwave Technology, 2010. **28**(24): p. 3512-3518.